

3. (Canceled).

4. (Amended) The sheet-like board member as defined in claim 1, further comprising:
a wiring disposed on said second planar surface, wherein
the mask is formed on a region corresponding to the wiring integrally connected to one or more
of the first pads.

6. (Amended) The sheet-like board member as defined in claim 1, wherein the conductive
coating film is disposed in the semiconductor element mount region to form a die pad.

7. (Amended) The sheet-like board member as defined in claim 1, wherein the conductive
coating film is disposed on the second planar surface to form a passive element die pad and/or
outer lead electrode.

8. (Amended) The sheet-like board member as defined in claim 7, wherein a passive
element to be placed on the passive element die pad comprises a chip resistor or a chip capacitor.

9. (Amended) The sheet-like board member as defined in claim 1, wherein patterns which
are substantially identical with guide pins or guide holes into which the guide pins are inserted
are formed in mutually-opposing side of the sheet-like board member.

10. (Amended) The sheet-like board member as defined in claim 1, wherein the sheet-like
board member comprises a pressed metal.

11. (Amended) The sheet-like board member as defined in claim 1, wherein the sheet-like
board member is formed from a conductive foil, and the conductive film is formed of a material
different from that of the conductive foil.

12. (Amended) A sheet-like board member comprising:
a first planar surface;

a second planar surface disposed opposite to the first planar surface;
protuberances formed on said second planar surface;
a conductive film on each of said protuberances,
wherein the protuberances comprise a plurality of first pads in or in the vicinity of a
semiconductor element mount region defined on the second planar surface.

13. (Amended) The sheet-like board member as defined in claim 12, wherein the
protuberances comprise wirings integrally formed with the first pads.

14. (Amended) The sheet-like board member as defined in claim 13, wherein the
protuberances comprise second pads integrally formed with the wirings.

15. (Amended) The sheet-like board member as defined in claim 12, wherein the first
pads comprise bonding pads, or pads on which solder balls or bumps are mounted.

16. (Amended) The sheet-like board member as defined in claim 12, wherein the
protuberances comprise die pads provided in the semi-conductor element mount region.

17. (Amended) The sheet-like board member as defined in claim 12, wherein the
protuberances comprise passive element die pads and/or outer lead electrodes.

18 (Amended) The sheet-like board member as defined in claim 17, wherein a passive
element to be disposed on the passive element die pad comprises a chip resistor or chip
capacitor.

19. (Amended) The sheet-like board member as defined in claim 12, wherein patterns
which are substantially identical with guide pins or guide holes into which the guide pins are
inserted are formed in mutually-opposing sides of the sheet-like board member.

20. (Amended) The sheet-like board member as defined in claim 12, wherein the protuberances are arranged in a plurality of patterns as a unit, and the unit is arranged in a matrix pattern on the sheet-like board member.

21. (Amended) The sheet-like board member as defined in claim 12, wherein the sheet-like board member comprises mainly Cu, Al, an Fe-Ni alloy, a Cu-Al multi-layered member, or an Al-Cu-Al multi-layered member.

22. (Amended) The sheet-like board member as defined in claim 12, wherein [a] the conductive coating film is formed of material different from that of the protuberances and formed on the upper surfaces of the protuberances.

23. (Amended) The sheet-like board member as defined in claim 12, wherein side surfaces of the protuberances have an anchoring structure.

24. (Amended) The sheet-like board member as defined in claim 12, further comprising: the conductive film comprising an anvil-shaped structure in the vicinity of a top surface of each protuberance.

25. (Amended) The sheet-like board member as defined in claim 12, wherein the conductive film comprises Ni, Au, Ag or Pd.

26. (Amended) A sheet-like board member comprising:
a planar surface;
a sheet-like front side of predetermined thickness which is provided on the planar surface;
a plurality of first pads formed in or in the vicinity of a semiconductor element mount region defined on the planar surface;
protuberances formed on said planar surface and include wirings integrally formed with the first pads, said plurality of first pads and said protuberances formed within an

abutting region defined on said planar surface, said abutting region provided to contact with an upper metal mold. --

Please add claims 32 to 43.

-- 32. (New) The sheet-like board member of claim 26, wherein said planar surface having the protuberances, some of which semiconductor elements are disposed thereon, are all encapsulated in plastic.

33. (New) A sheet-like board member comprising:
a first planar surface;
a second planar surface disposed opposite to the first surface, said second planar surface having a semiconductor element mount region defined thereon; and
a mask for etching disposed on the second planar surface and having a pattern corresponding to a plurality of first pads formed in or in the vicinity of the semiconductor element mount region.

34. (New) The sheet-like board member as defined in claim 1, wherein the mask comprises a photoresist.

35. (New) The sheet-like board member as defined in claim 1, wherein the mask comprises a conductive film.

36. (New) The sheet-like board member as defined in claim 33, further comprising:
a wiring disposed on said second planar surface, wherein
the mask is formed on a region corresponding to the wiring integrally connected to one or more of the first pads.

37. (New) The sheet-like board member as defined in claim 33, wherein the first pads are bonding pads or pads on which solder balls are to be fixed.

38. (New) The sheet-like board member as defined in claim 33, wherein the conductive coating film is disposed in the semiconductor element mount region to form a die pad.

39. (New) The sheet-like board member as defined in claim 33, wherein the conductive coating film is disposed on the second planar surface to form a passive element die pad and/or outer lead electrode.

40. (New) The sheet-like board member as defined in claim 39, wherein a passive element to be placed on the passive element die pad comprises a chip resistor or a chip capacitor.

41. (New) The sheet-like board member as defined in claim 33, wherein patterns which are substantially identical with guide pins or guide holes into which the guide pins are inserted are formed in mutually-opposing side of the sheet-like board member.

42. (New) The sheet-like board member as defined in claim 33, wherein the sheet-like board member comprises a pressed metal.

43. (New) The sheet-like board member as defined in claim 33, wherein the sheet-like board member is formed from a conductive foil, and the conductive film is formed of a material different from that of the conductive foil.--

In the abstract:

Please replace the abstract with the following version.

-- A sheet-like board member has conductive coating films, such as first pads and die pads, formed on the member. The sheet-like board member can be half-etched by using the